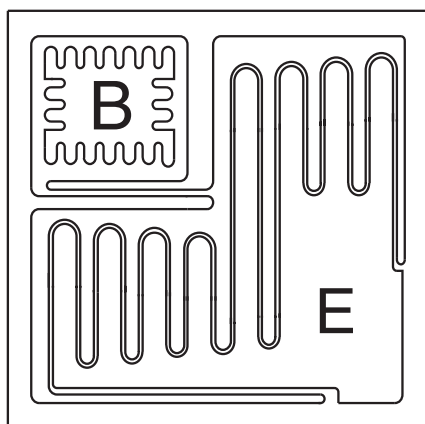


PROCESS DETAILS

Process	EPITAXIAL BASE
Die Size	195 X 195 MILS
Die Thickness	12 MILS
Base Bonding Pad Area	29 X 29 MILS
Emitter Bonding Pad Area	61 X 35 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Ti/Ni/Au - 6,000Å

GEOMETRY

BACKSIDE COLLECTOR R0

GROSS DIE PER 5 INCH WAFER

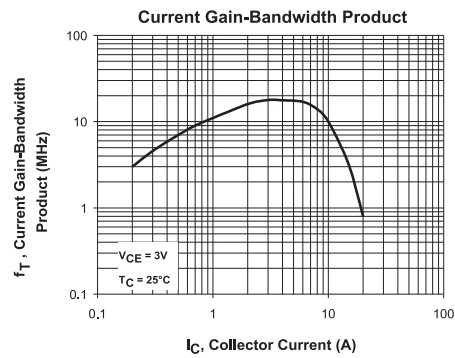
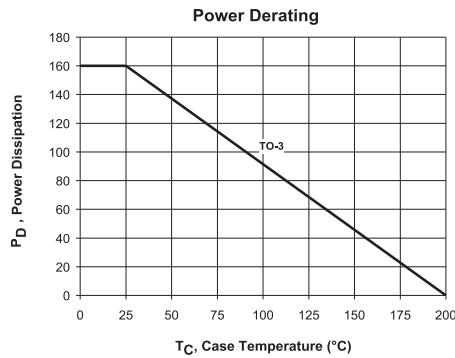
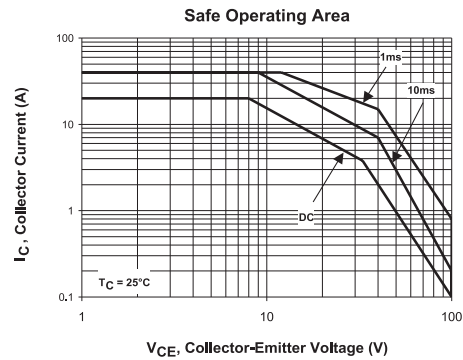
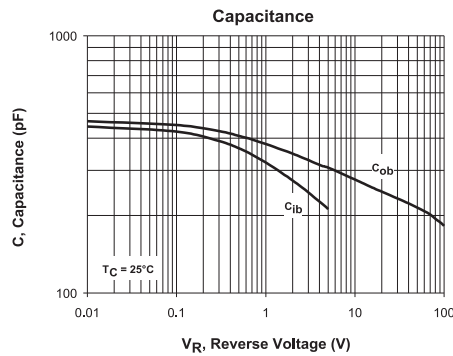
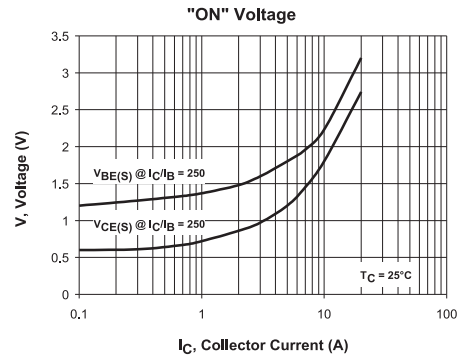
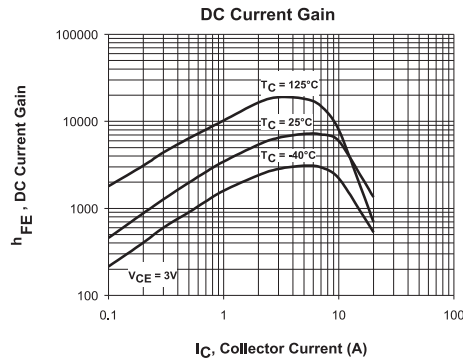
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PRINCIPAL DEVICE TYPES

MJ11011	2N6285
MJ11013	2N6286
MJ11015	2N6287

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